

Title (en)
POWDER AND PASTE FOR IMPROVING THE CONDUCTIVITY OF ELECTRICAL CONNECTIONS

Title (de)
PULVER UND PASTE ZUR ERHÖHUNG DER LEITFÄHIGKEIT ELEKTRISCHER VERBINDUNGEN

Title (fr)
POUDRE ET PÂTE POUR AMÉLIORER LA CONDUCTANCE DES CONNEXIONS ÉLECTRIQUES

Publication
EP 2904615 B1 20190508 (FR)

Application
EP 13780184 A 20131002

Priority
• FR 1202631 A 20121003
• FR 2013000258 W 20131002

Abstract (en)
[origin: WO2014053715A1] An electrical connection powder comprising particles obtained by pulverising a skeleton of open cell metal foam chosen from the group consisting of iron, cobalt, nickel and the alloys of same covered with at least one coating of tin or indium or one of the alloys of same. The paste is formed from this powder dispersed in a binder such as grease. The powder or paste is particularly useful for improving the conductivity of an electrical connection consisting of a terminal (20) linked to a cable (24) consisting of a plurality of strands (30, 32, 34) by means of a crimping ring (26).

IPC 8 full level
H01B 1/16 (2006.01); **B22F 9/04** (2006.01); **H01B 1/02** (2006.01); **H01R 4/20** (2006.01); **H01R 4/30** (2006.01); **H01R 4/62** (2006.01); **H01R 13/03** (2006.01)

CPC (source: EP US)
B22F 9/04 (2013.01 - US); **H01B 1/02** (2013.01 - EP US); **H01B 1/16** (2013.01 - EP US); **H01B 13/00** (2013.01 - US); **H01R 13/03** (2013.01 - EP US); **B22F 2009/046** (2013.01 - US); **H01R 4/20** (2013.01 - EP US); **H01R 4/304** (2013.01 - EP US); **Y10T 428/12181** (2015.01 - EP US)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
FR 2996348 A1 20140404; **FR 2996348 B1 20150515**; AU 2013326368 A1 20150507; AU 2013326368 B2 20170504; CA 2886818 A1 20140410; CA 2886818 C 20210216; CN 104903972 A 20150909; EP 2904615 A1 20150812; EP 2904615 B1 20190508; HK 1214885 A1 20160805; JP 2015537115 A 20151224; JP 6251274 B2 20171220; KR 102103964 B1 20200423; KR 20150092084 A 20150812; US 2015262723 A1 20150917; US 9748014 B2 20170829; WO 2014053715 A1 20140410

DOCDB simple family (application)
FR 1202631 A 20121003; AU 2013326368 A 20131002; CA 2886818 A 20131002; CN 201380063239 A 20131002; EP 13780184 A 20131002; FR 2013000258 W 20131002; HK 16102737 A 20160309; JP 2015535080 A 20131002; KR 20157008323 A 20131002; US 201314433568 A 20131002